

TENTATIVE

CM450TJ-24NF

Pre.	S.Uchida	Rev	D	K.Kurachi
Apr.	M.Yamamoto July 31.'01			M.Yamamoto Mar.14.'03

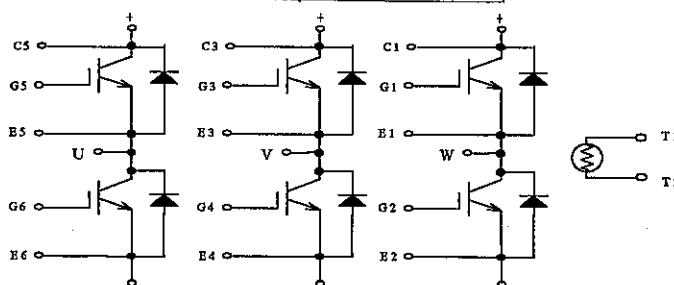
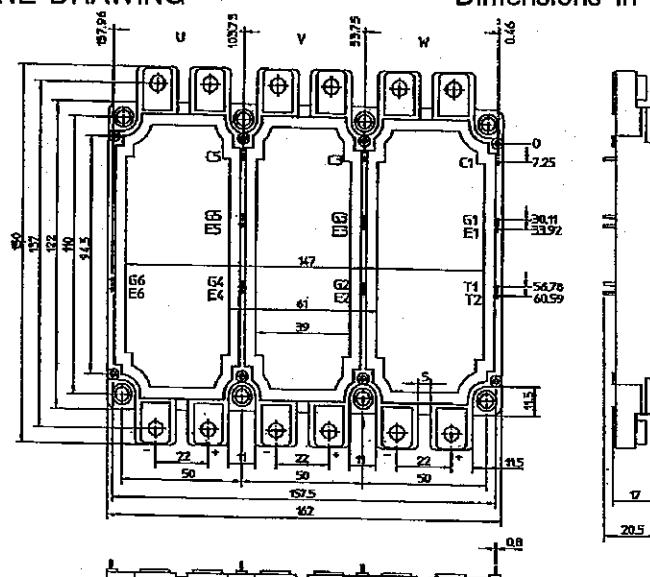
HIGH POWER SWITCHING USE

Notice : This is not a final specification. Some parametric limits are subject to change.

CM450TJ-24NF

OUTLINE DRAWING

Dimensions in mm



CIRCUIT DIAGRAM

APPLICATION

General purpose inverters & Servo controls,etc

ABSOLUTE MAXIMUM RATINGS ($T_j = 25^\circ\text{C}$)

Symbol	Item	Conditions	Ratings	Units
V_{CES}	Collector-emitter voltage	G-E Short	1200	V
V_{GES}	Gate-emitter voltage	C-E Short	± 20	V
I_c	Collector current	DC, $T_c = 96^\circ\text{C}$ *1	450	A
		Pulse ②	900	
I_E ①	Emitter current		450	A
		Pulse ②	900	
I_{EM} ①				
P_c ③	Maximum collector dissipation	$T_c = 25^\circ\text{C}$	3040	W
T_j	Junction temperature		-40~+150	°C
T_{stg}	Storage temperature		-40~+125	°C
V_{iso}	Isolation voltage	Main terminal to base plate, AC 1 min.	2500	V
—	Torque strength	Main terminal M6	3.5~4.5	N·m
—	Torque strength	Mounting holes M5	2.5~3.5	N·m
—	Weight	Typical value	1100	g

APPLICATION NOTE

MITSUBISHI<IGBT MODULE>

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HIGH POWER SWITCHING USE

ELECTRICAL CHARACTERISTICS ($T_j = 25^\circ\text{C}$)

Symbol	Item	Conditions	Min.	Typ.	Max.	Units
I_{CES}	Collector cutoff current	$V_{CE}=V_{CES}, V_{GE}=0\text{V}$	—	—	2	mA
$V_{GE(\text{th})}$	Gate-emitter threshold voltage	$I_C=45\text{mA}, V_{CE}=10\text{V}$	6	7	8	V
I_{GES}	Gate leakage current	$V_{GE}=V_{GES}, V_{CE}=0\text{V}$	—	—	0.5	μA
$V_{CE(\text{sat})}$	Collector to emitter saturation voltage	$T_j = 25^\circ\text{C}$	$I_C = 450\text{A}$	—	2.0**	2.6**
		$T_j = 125^\circ\text{C}$	$V_{GE}=15\text{V}$	—	2.2**	—
C_{IES}	Input capacitance	$V_{CE}=10\text{V}$	—	—	70	nF
C_{OES}	Output capacitance	$V_{GE}=0\text{V}$	—	—	8.1	
C_{RES}	Reverse transfer capacitance	—	—	—	1.5	
Q_G	Total gate charge	$V_{CC}=600\text{V}, I_C=450\text{A}, V_{GE}=15\text{V}$	—	2400	—	nC
$t_{d(on)}$	Turn-on delay time	$V_{CC}=600\text{V}, I_C=450\text{A}$	—	—	500	ns
t_r	Turn-on rise time	$V_{GE1}=V_{GE2}=15\text{V}$	—	—	150	
$t_{d(off)}$	Turn-off delay time	$R_G=0.7\Omega$, Inductive load	—	—	600	
t_f	Turn-off fall time	switching operation	—	—	300	
$t_{rr} \text{ (1)}$	Reverse recovery time	$I_E=450\text{A}$	—	—	250	ns
$Q_{RR} \text{ (1)}$	Reverse recovery charge	—	—	15	—	μC
$V_{EC} \text{ (1)}$	Emitter-collector voltage	$I_E=450\text{A}, V_{GE}=0\text{V}$	—	—	3.2**	V
$R_{th(j-c')Q}$	Thermal resistance [*]	IGBT part	—	—	0.041	$^\circ\text{C}/\text{W}$
$R_{th(j-c')R}$		FWDI part	—	—	0.048	
$R_{th(c-f)}$	Contact thermal resistance	Case to fin, Thermal compound Applied (1/6module)	—	0.048 ²	—	
R_G	External gate resistance	—	0.7	—	7	Ω

** : without package drop voltage

*1: T_c' measured point is just under the chips.

If you use this value, $R_{th(f-a)}$ should be measured just under the chips.

*2: Typical value is measured by using Shin-etsu Silicone "G-746".

Thermistors part

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
R_{TH}	Resistance	$T_c=25^\circ\text{C}$	—	5	—	$\text{k}\Omega$
B	B Constant	Resistance at $25^\circ\text{C}, 50^\circ\text{C}$ ⑤	—	3375	—	K

① $I_E, V_{EC}, t_{rr}, Q_{RR}$ & die/dt represent characteristics of the anti-parallel, emitter to collector free-wheel diode (FWDI).

② Pulse width and repetition rate should be such that the device junction temp. (T_j) dose not exceed $T_{j\max}$ rating.

③ Junction temperature (T_j) should not increase beyond 150°C .

④ Pulse width and repetition rate should be such as to cause neglible temperature rise.

⑤ $B = (\ln R_1 - \ln R_2) / (1/T_1 - 1/T_2)$ R_1 : Resistance at $T_1(\text{K})$ R_2 : Resistance at $T_2(\text{K})$